H263-S67-AAW1







High Density Server - 2U 4-Node DP 8-Bay Gen5 NVMe/SATA/SAS-4 3000W



Key Features

- 2U 4-node rear access server system
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors per node
- Dual Intel® Xeon® CPU Max Series per node
- 8-Channel DDR5 RDIMM, 16 x DIMMs per node
- Dual ROM Architecture
- 1 x Chassis Management LAN port
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Applications

High-Performance Computing Server, High Converged Server...

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D850 mm)	PCIe Expansion Slots	4 x LP PCIe Gen5 x16 4 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
Motherboard	MS63-HD1		
СРИ	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor per node, TDP up to 270W - At 35°C ambient with no OCP support, TDP up to 350W - At 30°C ambient, TDP up to 350W	I/O Ports	Front: 1 x CMC status LED, 1 x CMC reset button Rear: 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC port
		Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
OS Compatibility	OS Support List	TPM	4 x TPM headers (SPI), Optional TPM2.0 kit: CTM010
, ,		Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply Available for 2+1 redundant power supply configuration (optional) AC Input: 100-240V *The system power supply requires C19 power cord.
Socket	8 x LGA 4677 (Socket E)		
Chipset	Intel® C741		
Memory	8-Channel DDR5 RDIMM, 64 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
LAN		System Fans	4 x 80x80x80mm
LAN	$4 \times 10/100/1000$ Mbps Management LAN $1 \times Chassis$ Management LAN $[1]$ [1] Please refer to optional parts for ring topology support.	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Video	Integrated in ASPEED [®] AST2600 x 4 - 4 x VGA ports	Packaging Content 1 x H263-S67-AAW1 8 x CPU heatsinks 24 x Carriers 1 x 3-Section Rail kit	
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS-4 [1] Optional internal M.2: 4 x M.2 (2280/22110), PCIe Gen4 x4 [1] SAS card is required to support SAS drives.		
		Ordering Part Numbers	6NH263S67DR000ABW1*
RAID	Intel [®] SATA RAID 0/1/10/5 Onboard VROC key header	Optional Parts	- M.2 riser card - CMTP061: 9CMTP061NR-00* - Ring topology kit (10-kit package): 6NH263S62S1000AAN11



